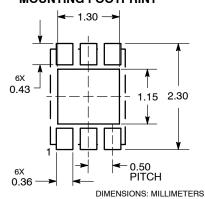


RECOMMENDED MOUNTING FOOTPRINT



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

WDFN6 1.6x2.0, 0.5P

DATE 17 MAY 2012

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

		====	
	MILLIMETERS		
DIM	MIN	MAX	
Α	0.60	0.80	
A1	0.00	0.05	
А3	0.20 REF		
b	0.20	0.40	
D	1.60 BSC		
D2	1.10	1.30	
E	2.00 BSC		
E2	0.95	1.15	
е	0.50 BSC		
K	0.20		
L	0.15	0.35	
L1		0.10	

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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